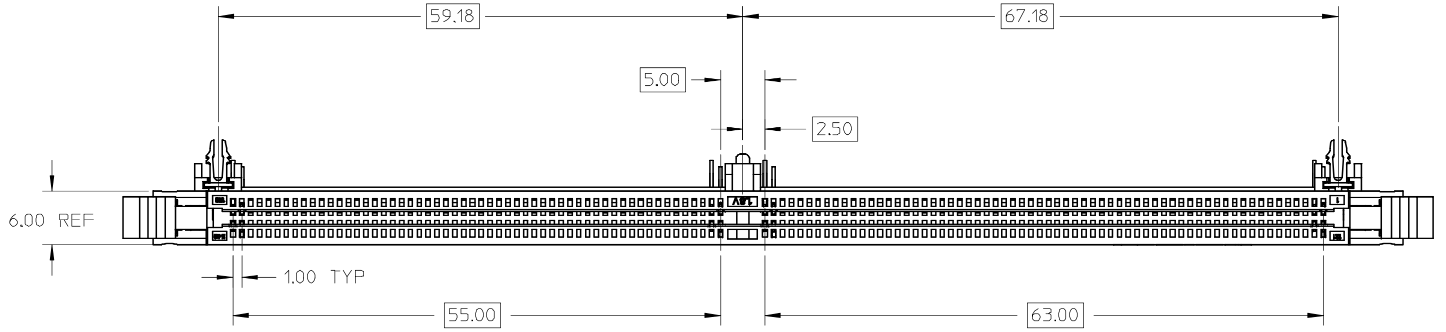
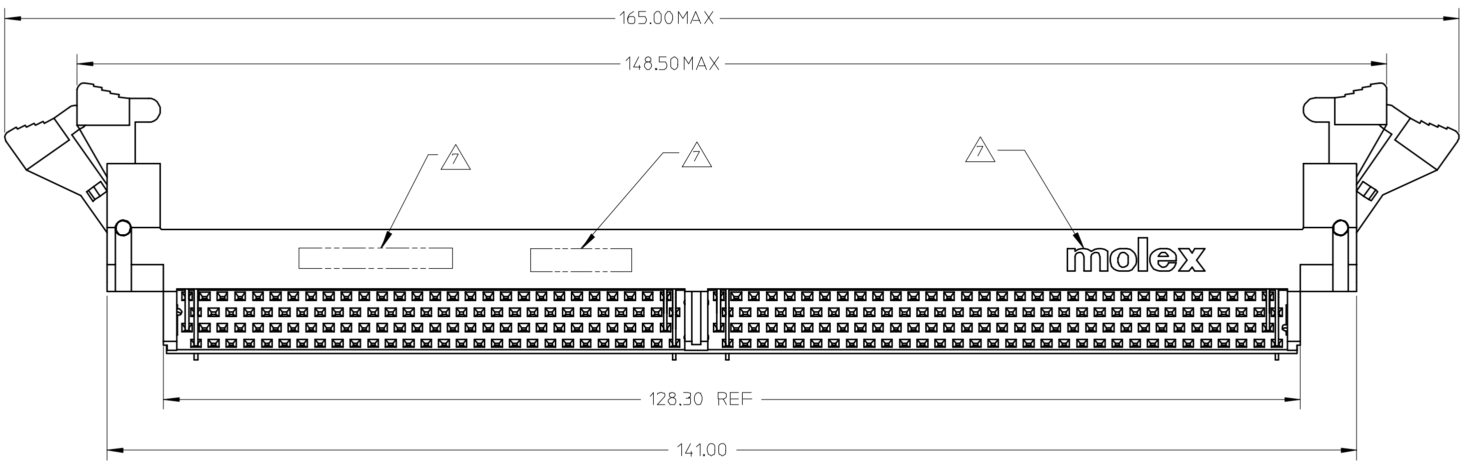
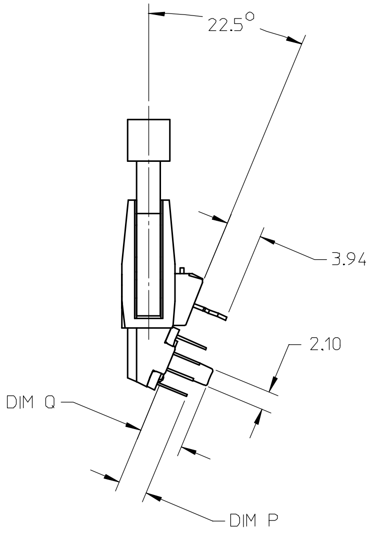






NOTES :

1. MATERIALS : HOUSING, BASEPLATE AND LATCH.
   - HIGH TEMP THERMOPLASTIC, UL94-0.
   TERMINALS & FORKLOCK - COPPER ALLOY.
2. PLATING : CONTACT AREA - SEE TABLE IN SHEET 5.
   SOLDERTAIL - SEE TABLE IN SHEET 5.
3. CARD SLOT ACCEPTS 1.27+/-0.10MM MODULE THICKNESS (MEASURED OVER PC PADS).
4. REFER TO PRODUCT SPECIFICATION , PS-87916-001 FOR PERFORMANCE SPECIFICATION.
5. RECOMMENDED MODULE CARD LAYOUT SHALL BE AS PER JEDEC MO-237.
6. PRODUCT SHALL BE PACKED IN TRAY.
7. MOLEX LOGO, DATE CODE & PART NUMBER INDICATED ON HOUSING.

REV	DESCRIPTION
A1	ADDED OPTION EC NO: S2008-0329 DRWN:CCTEH 2007/10/24 CH'KD:YTYANG01 2007/10/24 APPR:SHLENI 2007/10/25

QUALITY SYMBOLS
▼=0
▽C=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ± 5 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

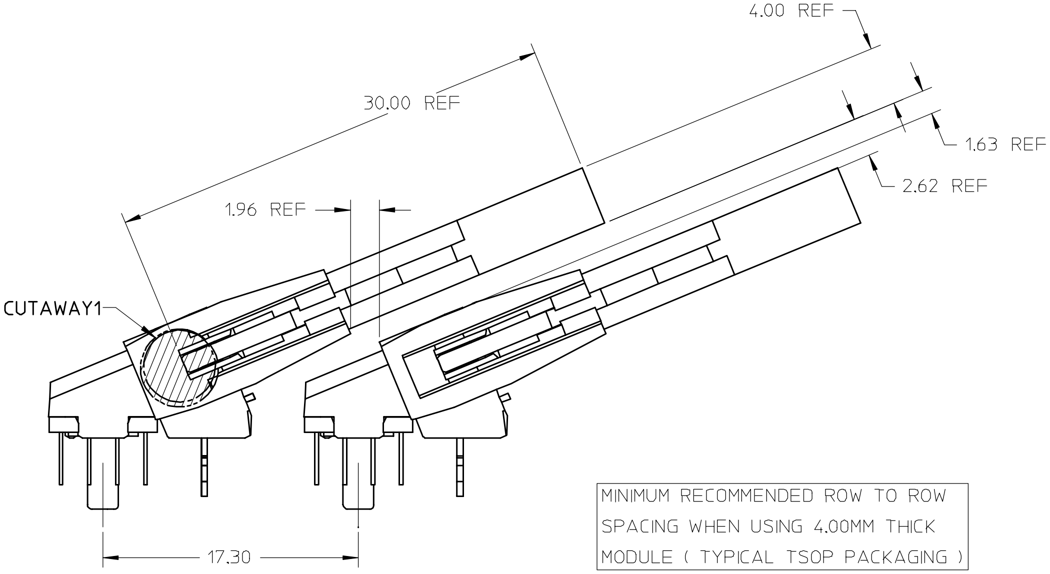
DIMENSION STYLE: MM ONLY	SCALE: NTS	DESIGN UNITS: METRIC
DRAWN BY: JTAN	DATE: 2004/05/11	
CHECKED BY: MLONG	DATE: 2004/06/11	
APPROVED BY: GGLEE	DATE: 2004/06/11	
MATERIAL NO.: SEE TABLE	DOCUMENT NO.: SD-87916-001	SHEET NO.: 1 OF 5

THIRD ANGLE PROJECTION

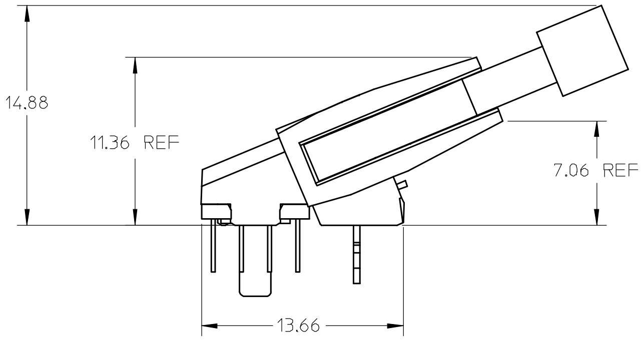
TITLE
DDR2 DIMM, 1.00MM PITCH 240 CKTS, 22.5 DEG

MOLEX INCORPORATED

SIZE A3



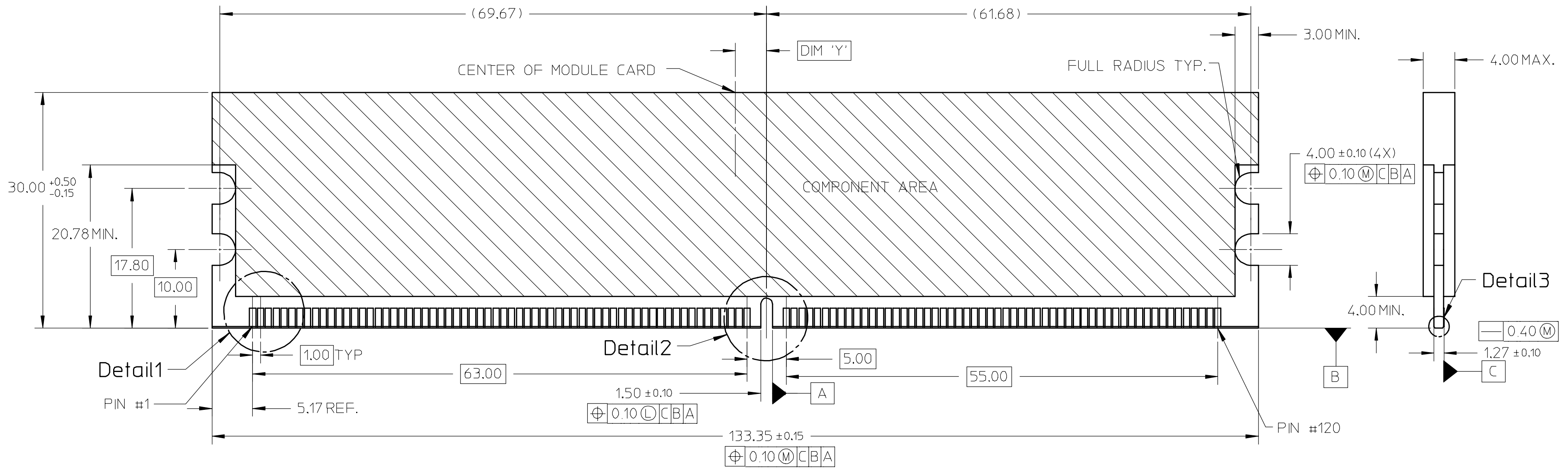
MINIMUM RECOMMENDED ROW TO ROW
SPACING WHEN USING 4.00MM THICK
MODULE (TYPICAL TSOP PACKAGING)



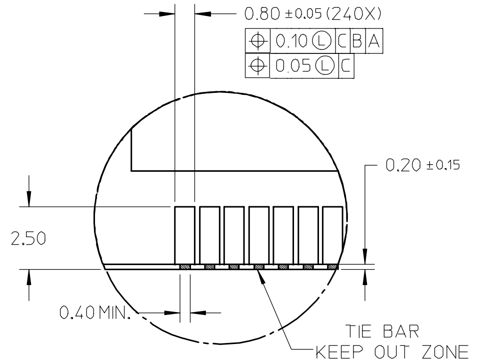
REV	DESCRIPTION		
A1	ADDED OPTION EC NO: S2008-0329 DRWN:CCTEH CH'KD:YTYANG01 APPR:SHLENI	2007/10/24 2007/10/24 2007/10/25	

QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	mm	INCH
▼=0	4 PLACES	± ---	± ---
Ⓒ=0	3 PLACES	± ---	± ---
	2 PLACES	± 0.25	± ---
	1 PLACE	± ---	± ---
	ANGULAR ± 5 °		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		

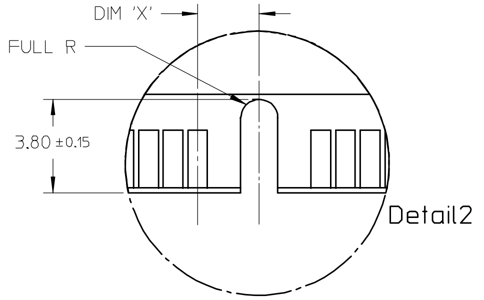
DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
DRAWN BY JTAN	DATE 2004/05/11	TITLE	DDR2 DIMM, 1.00MM PITCH 240 CKTS, 22.5 DEG
CHECKED BY MLONG	DATE 2004/06/11		
APPROVED BY GGLEE	DATE 2004/06/11	molex	MOLEX INCORPORATED
MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-87916-001	SHEET NO. 2 OF 5
SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

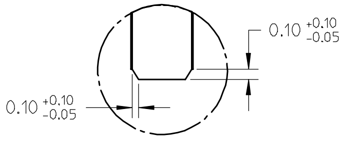


RECOMMENDED MODULE LAYOUT



Detail1





Detail3

KEY LOCATION	VOLTAGE	DIM 'X'	DIM 'Y'
CENTER	1.8V	2.50	4.00

ADDED OPTION
EC NO: S2008-0329
DRWN:CCTEH 2007/10/24
CH'KD:YTYANG01 2007/10/24
APPR:SHLENI 2007/10/25
DESCRIPTION
A1
REV

QUALITY SYMBOLS
▼=0
▽=0

GENERAL TOLERANCES
(UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---

ANGULAR ± 5 °

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY	SCALE: NTS	DESIGN UNITS: METRIC

THIRD ANGLE PROJECTION

	NAME	DATE
DRAWN BY	JTAN	2004/05/11
CHECKED BY	MLONG	2004/06/11
APPROVED BY	GGLEE	2004/06/11

TITLE
DDR2 DIMM, 1.00MM PITCH 240 CKTS, 22.5 DEG

MOLEX INCORPORATED

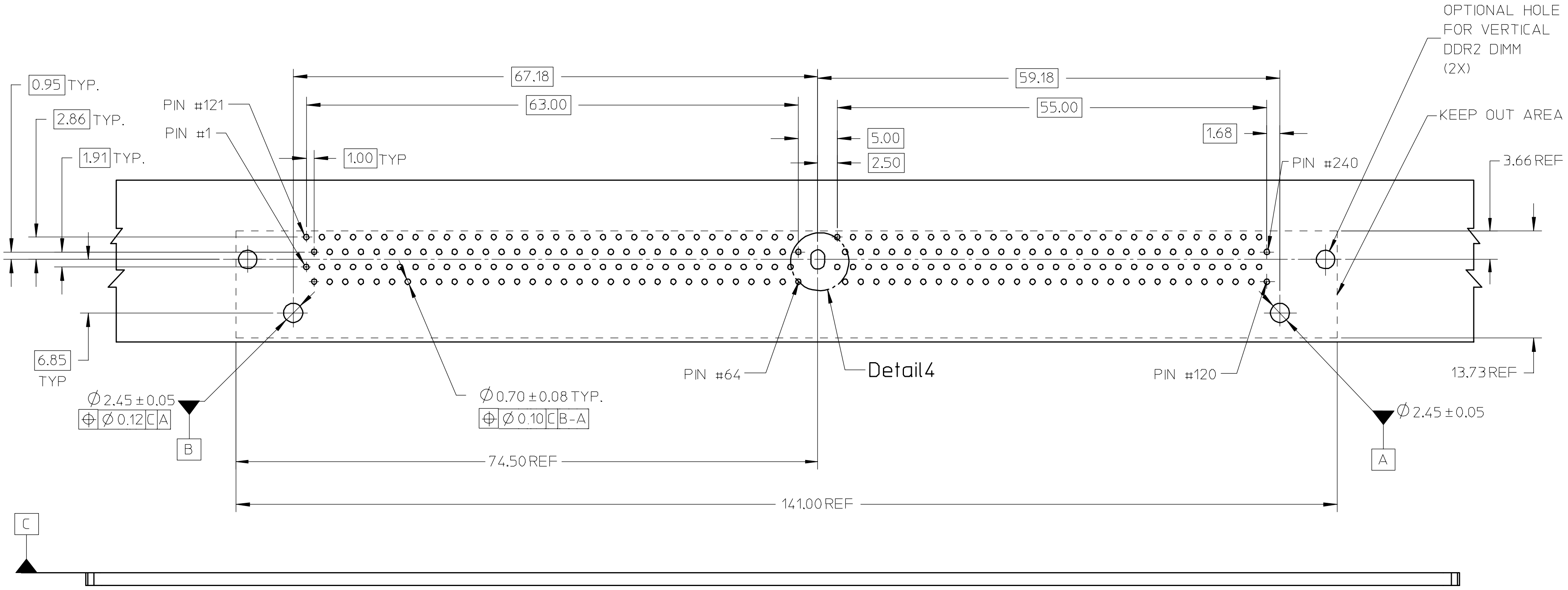
MATERIAL NO.: SEE TABLE

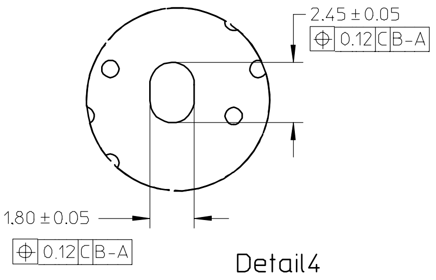
DOCUMENT NO.: SD-87916-001

SHEET NO.: 3 OF 5

SIZE: A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION





Detail4

ADDED OPTION EC NO: S2008-0329 DRWN:CCTEH 2007/10/24 CH'KD:YTYANG01 2007/10/24 APPR:SHLENI 2007/10/25	DESCRIPTION	
A1	REV	

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES
(UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ± 5 °		

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
DRAWN BY JTAN	DATE 2004/05/11	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 22.5 DEG	
CHECKED BY MLONG	DATE 2004/06/11		
APPROVED BY GGLEE	DATE 2004/06/11	MOLEX INCORPORATED	
MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-87916-001	SHEET NO. 4 OF 5
SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

PART NO.	VOLTAGE KEY	DIM 'P'	DIM 'Q'	RECOMMENDED PCB THICKNESS	CONTACT AREA PLATING	SOLDERTAIL PLATING
87916-0001	1.8V	2.79	3.18	1.57	0.76uM/ 30u" GOLD OVER 1.27uM/ 50u" MIN NICKEL	2.54uM/ 100u" MIN. TIN OVER 1.27uM/ 50u" MIN NICKEL
87916-0011		3.18	4.83	2.36		
87916-0111		4.00		3.20		

REV	DESCRIPTION		
A1	ADDED OPTION EC NO: S2008-0329 DRWN:CCTEH CH'KD:YTYANG01 APPR:SHLENI		2007/10/24 2007/10/24 2007/10/25

QUALITY SYMBOLS
▼=0
▽ C =0

GENERAL TOLERANCES
(UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---

ANGULAR ± 5 °

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: NTS
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

		DATE
DRAWN BY	JTAN	2004/05/11
CHECKED BY	MLONG	2004/06/11
APPROVED BY	GGLEE	2004/06/11

TITLE
DDR2 DIMM, 1.00MM PITCH
240 CKTS, 22.5 DEG

molex MOLEX INCORPORATED

MATERIAL NO. SEE TABLE
DOCUMENT NO. SD-87916-001
SHEET NO. 5 OF 5
SIZE A3